Switching Transistors

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	15	Vdc
Collector - Emitter Voltage	V _{CES}	40	Vdc
Collector - Base Voltage	V _{CBO}	40	Vdc
Emitter - Base Voltage	V _{EBO}	4.5	Vdc
Collector Current – Continuous	I _C	200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 CASE 318 STYLE 6

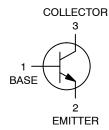


MARKING

xxx = M1J or 1JA M = Date Code* • = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.



ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT2369LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT2369LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SMMBT2369LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT2369ALT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBT2369ALT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

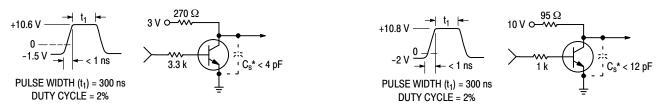
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 3) (I _C = 10 mAdc, I _B = 0)	V _{(BR)CEO}	15	_	_	Vdc
Collector – Emitter Breakdown Voltage ($I_C = 10 \mu Adc$, $V_{BE} = 0$)	V _{(BR)CES}	40	-	_	Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc$, $I_E = 0$)	V _(BR) CBO	40	-	_	Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$)	V _{(BR)EBO}	4.5	-	_	Vdc
Collector Cutoff Current $(V_{CB} = 20 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 20 \text{ Vdc}, I_E = 0, T_A = 150^{\circ}\text{C})$	I _{CBO}	- -	- -	0.4 30	μAdc
Collector Cutoff Current MMBT2369A (V _{CE} = 20 Vdc, V _{BE} = 0)	I _{CES}	-	-	0.4	μAdc
ON CHARACTERISTICS		*	•		
DC Current Gain (Note 3) $ \begin{array}{l} \text{MMBT2369 (I_C=10 \ mAdc, V_{CE}=1.0 \ Vdc)} \\ \text{MMBT2369A (I_C=10 \ mAdc, V_{CE}=1.0 \ Vdc)} \\ \text{MMBT2369A (I_C=10 \ mAdc, V_{CE}=0.35 \ Vdc)} \\ \text{MMBT2369A (I_C=10 \ mAdc, V_{CE}=0.35 \ Vdc, T_{A}=-55^{\circ}\text{C})} \\ \text{MMBT2369A (I_C=30 \ mAdc, V_{CE}=0.4 \ Vdc)} \\ \text{MMBT2369A (I_C=100 \ mAdc, V_{CE}=2.0 \ Vdc)} \\ \text{MMBT2369A (I_C=100 \ mAdc, V_{CE}=1.0 \ Vdc)} \\ \end{array} $	h _{FE}	40 - 40 20 30 20 20	- - - - -	120 120 - - - -	-
Collector – Emitter Saturation Voltage (Note 3) MMBT2369 (I_C = 10 mAdc, I_B = 1.0 mAdc) MMBT2369A (I_C = 10 mAdc, I_B = 1.0 mAdc) MMBT2369A (I_C = 10 mAdc, I_B = 1.0 mAdc, I_A = +125°C) MMBT2369A (I_C = 30 mAdc, I_B = 3.0 mAdc) MMBT2369A (I_C = 100 mAdc, I_B = 10 mAdc)	V _{CE(sat)}	- - - -	- - - -	0.25 0.20 0.30 0.25 0.50	Vdc
Base – Emitter Saturation Voltage (Note 3) MMBT2369/A (I_C = 10 mAdc, I_B = 1.0 mAdc) MMBT2369A (I_C = 10 mAdc, I_B = 1.0 mAdc, T_A = -55°C) MMBT2369A (I_C = 30 mAdc, I_B = 3.0 mAdc) MMBT2369A (I_C = 100 mAdc, I_B = 10 mAdc)	V _{BE(sat)}	0.7 - - -	- - - -	0.85 1.02 1.15 1.60	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Output Capacitance ($V_{CB} = 5.0 \text{ Vdc}$, $I_E = 0$, $f = 1.0 \text{ MHz}$)	$C_{ m obo}$	-	_	4.0	pF
Small Signal Current Gain ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 100 \text{ MHz}$)	h _{fe}	5.0	_	_	-
SWITCHING CHARACTERISTICS			÷.		
Storage Time $(I_{B1} = I_{B2} = I_C = 10 \text{ mAdc})$	t _s	-	5.0	13	ns
Turn-On Time ($V_{CC} = 3.0 \text{ Vdc}$, $I_C = 10 \text{ mAdc}$, $I_{B1} = 3.0 \text{ mAdc}$)	t _{on}	_	8.0	12	ns
Turn-Off Time $(V_{CC}=3.0\ Vdc,\ I_C=10\ mAdc,\ I_{B1}=3.0\ mAdc,\ I_{B2}=1.5\ mAdc)$	t _{off}	_	10	18	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

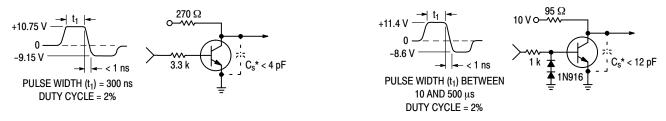
3. Pulse Test: Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2.0\%$.



*Total shunt capacitance of test jig and connectors.

Figure 1. ton Circuit - 10 mA

Figure 2. ton Circuit - 100 mA



*Total shunt capacitance of test jig and connectors.

Figure 3. toff Circuit - 10 mA

Figure 4. t_{off} Circuit – 100 mA

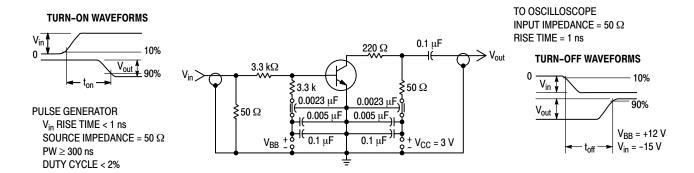


Figure 5. Turn-On and Turn-Off Time Test Circuit

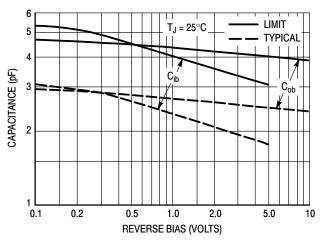


Figure 6. Junction Capacitance Variations

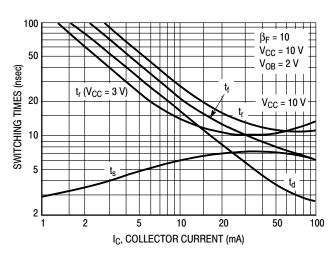


Figure 7. Typical Switching Times

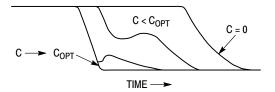


Figure 8. Turn-Off Waveform

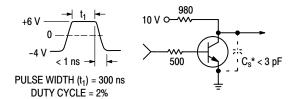


Figure 9. Storage Time Equivalent Test Circuit

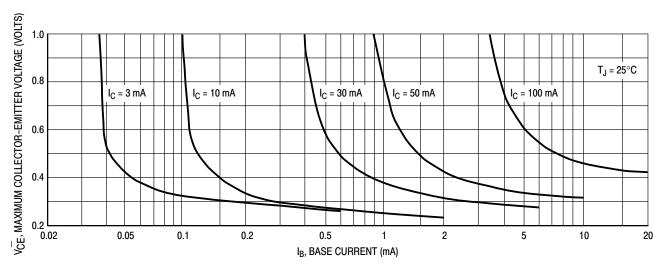


Figure 10. Maximum Collector Saturation Voltage Characteristics

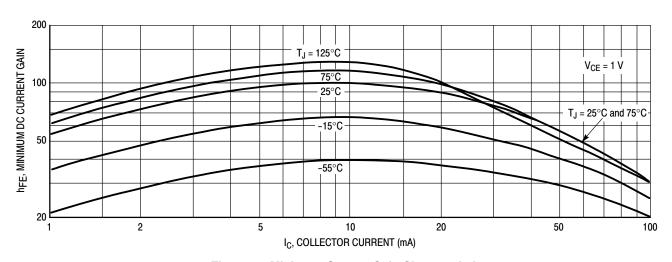


Figure 11. Minimum Current Gain Characteristics

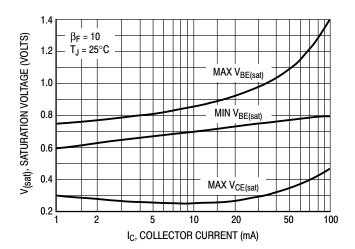


Figure 12. Saturation Voltage Limits

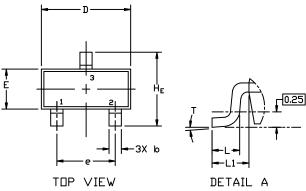




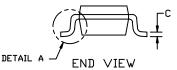
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DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	ETERS		INCHES		
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

GENERIC MARKING DIAGRAM*

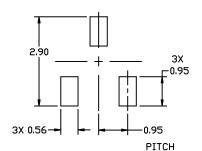


XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: I PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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